Fully Automatic BGA Rework Station with Max PCB Size 1200×700mm, Total Power 21000W and 13 Thermocouple Ports for Automatic BGA Rework Machine

Our Product Introduction

Basic Information

- Brand Name: WDS
- Model Number: WDS-1250



Product Specification

- Placement Accuracy: ±0.02mm
- Thermocouple Ports: 13 Pcs
- Max PCB Size: 1200×700mm
- Applicable Chip Size: 0.6×0.6mm - 80×120mm
- Temperature Control: Closed-loop K-type Thermocouple, Upper & Lower Independent Heating, ±1°C Accuracy
- Total Power: 21000W
- Power Supply: AC380V±10%, 50/60Hz
- Highlight: **1200×700mm BGA Rework Station**, **21000W BGA Rework Machine**, **13 Thermocouple Ports BGA Rework Station**



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Product Description

Product Description:

The Fully Automatic BGA Rework Station is a highly advanced and efficient piece of equipment designed specifically for the electronics manufacturing industry. Engineered to meet the rigorous demands of modern production lines, this station offers unparalleled precision and reliability in the rework and repair of Ball Grid Array (BGA) components. With its robust power supply and extensive capabilities, it is an essential tool for any facility aiming to enhance its manufacturing process and ensure the highest quality standards.

One of the standout features of this BGA Rework Station is its power supply specification. Operating on an AC380V±10% power source with a frequency of 50/60Hz, the station is built to deliver consistent and stable energy, which is crucial for maintaining the delicate thermal profiles required during rework processes. The total power rating of 21000W underscores its ability to handle demanding tasks with ease, providing rapid heating and precise temperature control to prevent damage to sensitive components.

The station is designed to accommodate a wide range of chip sizes, making it incredibly versatile. It supports chip sizes from as small as 0.6*0.6mm to as large as 80*120mm, allowing it to handle virtually any BGA component encountered in today's electronics manufacturing. This broad compatibility ensures that manufacturers can rely on a single piece of equipment for multiple applications, streamlining their workflow and reducing the need for additional machinery.

In terms of the printed circuit board (PCB) size, the Fully Automatic BGA Rework Station can manage PCBs up to 1200*700mm. This capability is particularly beneficial for manufacturing environments that deal with large and complex boards, as it eliminates size restrictions and enhances operational flexibility. The ability to work on larger PCBs without compromising accuracy or efficiency is a significant advantage for manufacturers focused on producing high-quality electronic products.

Temperature control is critical in any BGA rework process, and this station excels in that regard. It features 13 thermocouple ports, allowing for comprehensive monitoring and precise temperature measurement across multiple points on the PCB and component. This multi-point temperature sensing capability ensures that heat is evenly distributed, minimizing the risk of thermal damage and improving the overall success rate of rework operations. Such meticulous control is essential for maintaining the integrity of both the components and the PCB.

Equipped with an industry-grade HD monitor, the station provides real-time visual feedback and detailed process information to the operator. This high-definition display enhances user interaction and control, making it easier to monitor the rework process, adjust parameters as needed, and ensure optimal results. The clarity and responsiveness of the HD monitor contribute significantly to reducing errors and improving efficiency in manufacturing environments.

The Fully Automatic BGA Rework Station is designed with the needs of the manufacturing industry in mind, offering a combination of power, precision, and user-friendly features. Its fully automated operation reduces manual intervention, which not only speeds up the rework process but also minimizes the chances of human error. This automation capability is crucial for high-volume production settings where consistency and throughput are paramount.

In summary, this BGA Rework Station is an indispensable asset for electronics manufacturers seeking to elevate their production capabilities. Its high power supply, extensive chip and PCB size compatibility, advanced temperature monitoring with 13 thermocouple ports, and the inclusion of an industry-grade HD monitor make it a top-tier solution for BGA rework tasks. For manufacture environments that demand reliability, precision, and efficiency, this station delivers outstanding performance and helps maintain the highest quality standards in the industry.

Features:

Product Name: Fully Automatic BGA Rework Station

Applicable Chip Size: 0.6*0.6mm to 80*120mm

Full automatic operation for precise and efficient rework processes

Temperature Control: Closed-loop K-type Thermocouple with Upper & Lower Independent Heating

Temperature Accuracy: ±1°C for reliable and consistent results

Total Power: 21000W to ensure rapid heating and stable performance

Max PCB Size: 1200*700mm, suitable for large circuit boards

Equipped with 13 Thermocouple Ports for comprehensive temperature monitoring

Includes an HD monitor for clear and real-time process visualization

Designed for full automatic operation to minimize manual intervention and improve productivity

Technical Parameters:

Temperature Control	Closed-loop K-type Thermocouple, Upper & Lower Independent Heating, ±1°C Accuracy
Total Power	21000W
Placement Accuracy	±0.02mm
Applicable Chip Size	0.6*0.6mm - 80*120mm
Power Supply	AC380V±10%, 50/60Hz
Thermocouple Ports	13 Pcs
Max PCB Size	1200*700mm
Display	HD monitor, Large size touch screen
Temperature Control Feature	Accurate temperature control

Applications:

The WDS-1250 Fully Automatic BGA Rework Station by WDS is an advanced tool designed specifically for precise and efficient rework of Ball Grid Array (BGA) components. Its exceptional features make it ideal for a variety of product application occasions and scenarios, especially in electronics manufacturing, repair, and prototyping environments.

One of the standout attributes of the WDS-1250 is its capability to handle a wide range of chip sizes, from as small as 0.6*0.6mm up to large BGA components measuring 80*120mm. This versatility makes it suitable for applications involving both small and large BGA rework tasks, ensuring that technicians can rely on a single station for diverse projects without needing multiple machines.

Accurate temperature control is critical in BGA rework to prevent damage to sensitive electronic components. The WDS-1250 excels in this area with its closed-loop K-type thermocouple system, featuring 13 thermocouple ports for precise thermal monitoring. The upper and lower independent heating system maintains a temperature accuracy of ±1°C, which is essential for delicate soldering and desoldering processes. This level of control ensures consistent quality and reduces the risk of thermal damage to PCBs and components.

The placement accuracy of the WDS-1250 is another key feature, boasting an impressive ±0.02mm precision. This high positioning accuracy is vital for the alignment of BGA chips during rework, allowing for flawless solder joint formation and reliable electrical connections. Such precision is particularly important in high-density and fine-pitch BGA packages commonly found in modern electronic devices.

In addition to technical performance, the WDS-1250 incorporates user-friendly design elements such as a large size touch screen interface. This intuitive control panel simplifies operation, allowing technicians to easily set parameters, monitor the process, and make adjustments on the fly. The touch screen enhances workflow efficiency and reduces training time for new users.

The total power output of 21000W ensures rapid heating and stable temperature maintenance, making the station suitable for intensive industrial applications where speed and reliability are paramount. Consequently, the WDS-1250 is widely used in scenarios including electronics repair centers, manufacturing lines, R&D labs, and educational institutions where high precision and dependable rework capabilities are required.

Overall, the WDS-1250 Fully Automatic BGA Rework Station is an indispensable asset for professionals dealing with complex BGA rework tasks. Its combination of large BGA rework capability, accurate temperature control, high placement accuracy, and an easy-to-use large size touch screen makes it perfectly suited for demanding applications across various electronics industries.

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